

WHAT IS CLAIMED IS :

1. A composition for a polishing pad which comprises a water-insoluble matrix material containing a crosslinked polymer and a water-soluble particle dispersed in the water-insoluble matrix material.

2. The composition for a polishing pad according to claim 1, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble matrix material is broken at 80°C.

3. The composition for a polishing pad according to claim 2, wherein said water-insoluble matrix material is modified with at least one selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

4. The composition for a polishing pad according to claim 3, wherein said water-soluble particle is an organic water-soluble particle comprising at least one selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, and/or an inorganic water-soluble particle comprising at least one selected from the group consisting of potassium acetate, potassium nitrate, potassium carbonate, potassium bicarbonate, potassium chloride, potassium bromide, potassium phosphate and magnesium nitrate.

5. The composition for a polishing pad according to claim 4, wherein

the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

6. The composition for a polishing pad according to claim 1, wherein at least a part of said crosslinked polymer is a crosslinked rubber.

7. The composition for a polishing pad according to claim 6, wherein at least a part of said crosslinked rubber is crosslinked 1,2-polybutadiene.

8. The composition for a polishing pad according to claim 7, wherein said water-insoluble matrix material is modified with at least one selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

9. The composition for a polishing pad according to claim 8, wherein said water-soluble particle is an organic water-soluble particle comprising at least one selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, and/or an inorganic water-soluble particle comprising of at least one selected from the group consisting of potassium acetate, potassium nitrate, potassium carbonate, potassium bicarbonate, potassium chloride, potassium bromide, potassium phosphate and magnesium nitrate.

10. The composition for a polishing pad according to claim 9, wherein

the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

11. The composition for a polishing pad according to claim 1, wherein said water-soluble particle is provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part.

12. The composition for a polishing pad according to claim 11, wherein said water-soluble particle is an organic water-soluble particle comprising of at least one selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, and/or an inorganic water-soluble particle comprising of at least one selected from the group consisting of potassium acetate, potassium nitrate, potassium carbonate, potassium bicarbonate, potassium chloride, potassium bromide, potassium phosphate and magnesium nitrate.

13. The composition for a polishing pad according to claim 12, wherein the amount of said water-soluble particles is 10 to 90 % by volume based on 100 % by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

14. A polishing pad characterized in that at least a part of said polishing pad comprises the composition of a water-insoluble matrix

material containing a crosslinked polymer and a water-soluble particle dispersed in the water-insoluble matrix material.

15. A polishing pad according to claim 14, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble matrix material is broken at 80°C.

16. A polishing pad according to claim 15, wherein the Shore D hardness is 35 or more.

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